



# 100% Material Declaration Data Sheet FG324

PK153 (v1.2) September 21, 2006

Material Declaration Data Sheet

**Average Weight: 2.2251 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.0257</b>	<b>1.16%</b>
	Silicon	7440-21-3	100.00		0.0257	
<b>Die Attach Material</b>					<b>0.0033</b>	<b>0.15%</b>
	Silver	7440-22-4	78.00		0.0026	
	Resin	Trade Secret	22.00		0.0007	
<b>Mold Compound</b>					<b>0.7632</b>	<b>34.30%</b>
	Epoxy Resins	Trade Secret	12.00		0.0916	
	SiO2	60676-86-0	88.00	Filler	0.6716	
<b>Laminate</b>					<b>0.8270</b>	<b>37.17%</b>
	Laminate	Trade Secret	49.25		0.4073	
	Solder Mask	Trade Secret	7.70		0.0637	
	Copper	7440-50-8	40.91	Metal Layer	0.3383	
	Nickel	7440-02-0	1.79	Metal Layer	0.0148	
	Gold	7440-57-5	0.35	Metal Layer	0.0029	
<b>Bond Wire</b>					<b>0.0135</b>	<b>0.61%</b>
	Gold	7440-57-5	99.00		0.013347112	
	Silver	7440-22-4	0.0025		0.00000337	
	Copper	7440-50-8	0.0005		0.00000067	
	Iron	7439-89-6	0.0005		0.00000067	
	Calcium	7440-70-2	0.0020		0.00000270	
	Palladium	7440-05-3	0.9900		0.000133471	
	Magnesium	7439-95-4	0.0005		0.00000067	
<b>Solder Balls</b>					<b>0.5924</b>	<b>26.62%</b>
	Tin	7440-31-5	63.00		0.373212	
	Lead	7439-92-1	37.00		0.219188	

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1

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## Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/21/06	1.0	Initial release.
7/11/06	1.1	100% Material Declaration.
9/21/06	1.2	Updated component descriptions.